



**GENERAL DESCRIPTION**

HC138 is fabricated in the high-speed silicon gate CMOS technology. It has the high noise immunity and low power consumption of standard CMOS integrated circuits. It also offers speeds comparable to low power Schottky devices (LS-TTL).

HC138 devices can be used in high-performance memory-decoding or data routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory are

usually less than typical access time of the memory. This means the effective system delay introduced by the decoders is negligible.

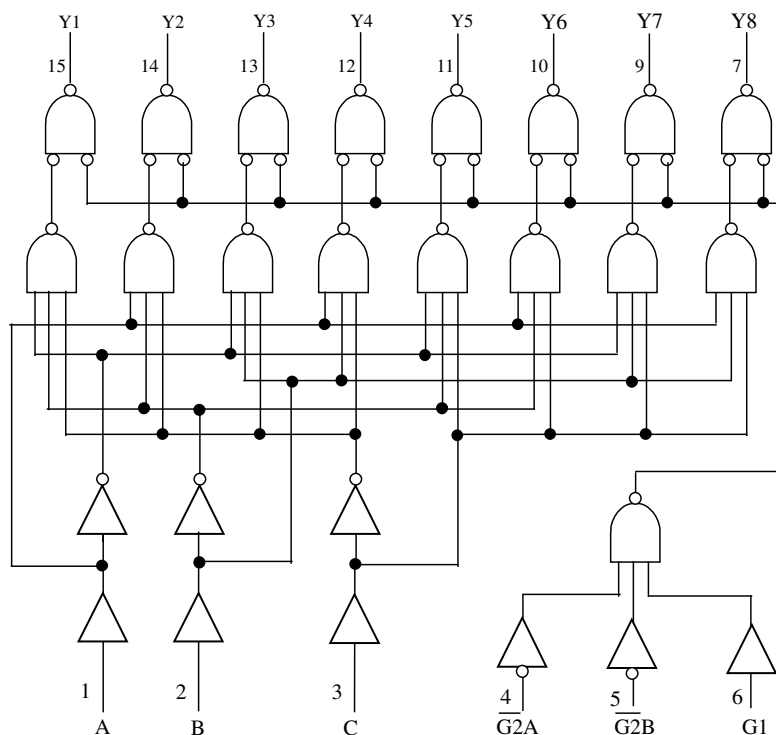
HC138 has 3 binary-select inputs (A, B, C). If the device is enable, these inputs determine which one of the eight outputs normally at high will go low. Two active low and one active high enables (G1, G2A, G2B) are provided to ease the cascading of decoders.

A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for de-multiplexing applications.

**FEATURES**

- Wide operating supply voltage range: 2-6V
- Output Drive at VDD = 5V :  $\pm 4\text{mA}$
- Typical propagation delay: 15ns
- Low input current:  $< 1\mu\text{A}$ .
- Low quiescent supply current: 80 $\mu\text{A}$  maximum
- Incorporate 3 enable inputs to simplify cascading and/or data reception
- For high-speed memory decoders and data-transmission systems

**LOGIC DIAGRAM**



## FUNCTIONAL DESCRIPTION

## Truth Table

INPUTS			OUTPUTS										
ENABLE		SELECT											
G1	$\overline{G2A}$	$\overline{G2B}$	C	B	A	Y1	Y2	Y3	Y4	Y5	Y6	Y7	Y8
X	H	X	X	X	X	H	H	H	H	H	H	H	H
X	X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	L	H	H	H	H	L	H	H	H	H	H
H	L	L	H	L	L	H	H	H	H	L	H	H	H
H	L	L	H	L	H	H	H	H	H	H	L	H	H
H	L	L	H	H	L	H	H	H	H	H	H	L	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L

H = High Level (steady state). L= Low Level (steady state)

X = Irrelevant (any input, including transitions)

## ABSOLUTE MAXIMUM RATINGS

Parameter	Value	Unit
DC supply voltage (V <sub>DD</sub> )	- 0.5 ~ + 7.0	V
DC input or output Voltage (V <sub>IN</sub> , V <sub>OUT</sub> )	-0.5 to V <sub>DD</sub> +0.5	V
DC Current Drain per pin, any output (I <sub>out</sub> )	±25	mA
DC Current Drain per pin, V <sub>DD</sub> or GND (I <sub>cc</sub> )	±50	mA
Storage Temperature( T <sub>STG</sub> )	-65 ~ +150	°C

**Note:** 1. Absolute maximum ratings are those values beyond which the safety of the device cannot be guaranteed.

## RECOMMENDED OPERATING CONDITIONS

Parameter		Min.	Normal	Max.	Unit
DC Supply Voltage (V <sub>DD</sub> )		2.0	5.0	6.0	V
V <sub>IH</sub> High-level Input Voltage	V <sub>DD</sub> =2.0V	1.5			V
	V <sub>DD</sub> =4.5V	3.15			
	V <sub>DD</sub> =6.0V	4.2			
V <sub>IL</sub> Low-level Input Voltage	V <sub>DD</sub> =2.0V			0.5	V
	V <sub>DD</sub> =4.5V			1.35	
	V <sub>DD</sub> =6.0V			1.8	
V <sub>I</sub> Input Voltage		0		V <sub>DD</sub>	V
V <sub>O</sub> Output Voltage		0		V <sub>DD</sub>	V
Operating Temperature (TA)	74HC138	-40		+85	°C
	54HC138	-55		+125	°C
Input Rise/Fall Times (tr, tf)	V <sub>DD</sub> =2.0V			1000	ns
	V <sub>DD</sub> =4.5V			500	
	V <sub>DD</sub> =6.0V			400	

**Note:** 2. All unused inputs of the device must be held at V<sub>DD</sub> or GND to ensure proper device operation.

**DC ELECTRICAL CHARACTERISTICS**

(unless otherwise specified)

Parameter	Test Conditions		VDD	TA =25 °C			54HC138		74HC138		Unit
				Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
VOH	VI=VIH or VIL	IOH = -20µA	2.0V	1.9	1.998		1.9		1.9	V	
			4.5V	4.4	4.499		4.4	4.4			
			6.0V	5.9	5.999		5.9	5.9			
		IOH = -4mA	4.5V	3.98	4.3		3.7	3.84			
		IOH = -5.2mA	6.0V	5.48	5.8		5.2	5.34			
VOL	VI= VIH or VIL	IOL = 20µA	2.0V		0.002	0.1		0.1	0.1	V	
			4.5V		0.001	0.1		0.1	0.1		
			6.0V		0.001	0.1		0.1	0.1		
		IOL = 4mA	4.5V		0.17	0.26		0.4	0.33		
		IOL = 5.2mA	6.0V		0.15	0.26		0.4	0.33		
I <sub>I</sub>	VI=VDD or 0		6.0V		±0.1	±100		±1000	±1000	nA	
I <sub>CC</sub>	VI=VDD or 0 IO =0		6.0V			8		160	80	µA	
C <sub>i</sub>			2~6V		3	10		10	10	pF	

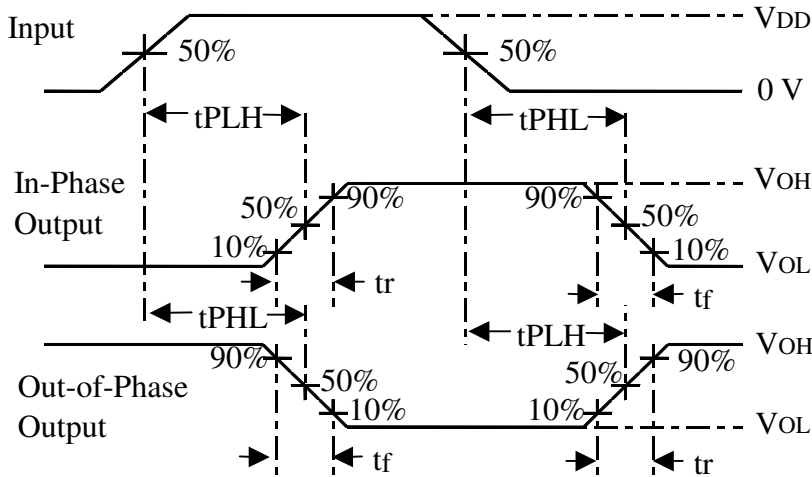
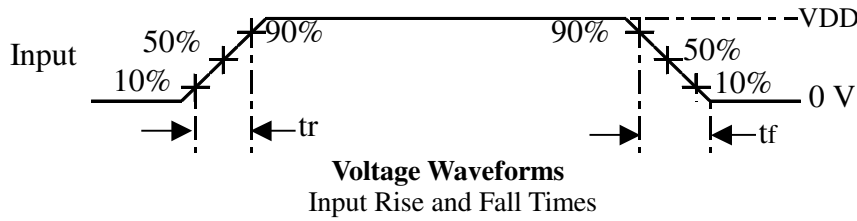
**AC ELECTRICAL CHARACTERISTICS (CL = 50pF)**

Parameter	From (Input)	To (Output)	VDD	TA =25 °C			54HC138		74HC138		Unit
				Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
t <sub>pd</sub>	A,B or C	Any Y	2.0V		67	180		270		225	ns
			4.5V		18	36		54		45	
			6.0V		15	31		46		38	
	Enable	Any Y	2.0V		66	155		235		195	ns
			4.5V		18	31		47		39	
			6.0V		15	26		40		33	
t <sub>t</sub>		Any	2.0V		38	75		110		95	ns
			4.5V		8	15		22		19	
			6.0V		6	13		19		16	

Parameter	Test Conditions	Typ.	Unit
C <sub>pd</sub> Power Dissipation Capacitance	TA =25 °C , No Load	85	pF

**Note 3:** C<sub>PD</sub> determines the no load dynamic power consumption , P<sub>D</sub>=C<sub>PD</sub>· VDD<sup>2</sup>·f + I<sub>CC</sub> ·VDD, and the no load dynamic current consumption, I<sub>S</sub> = CPD· VDD·f<sub>i</sub> + I<sub>CC</sub>

AC SWITCHING WAVEFORM

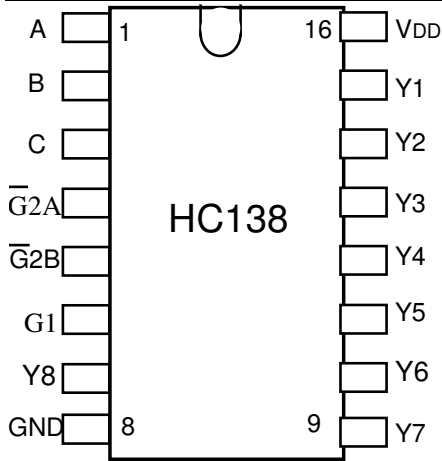


**NOTES 4:**

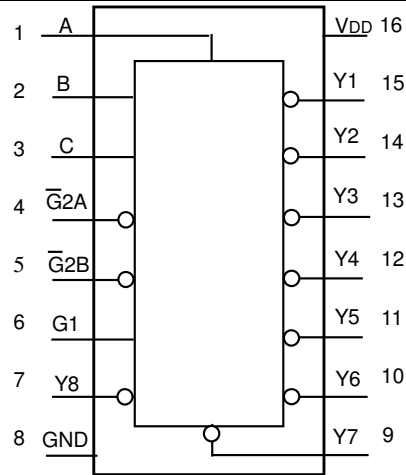
- 1) CL includes probe and test-fixture capacitance.
- 2) Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  
PRR ≤ 1 MHz, Z<sub>O</sub> = 50Ω, tr = 6 ns, tf = 6 ns.
- 3) The outputs are measured one at a time with one input transition per measurement.
- 4) tPLH and tPHL are the same as tpd.

**PIN DESCRIPTION**

PIN NO.	SYMBOL	DESCRIPTION
1, 2, 3	A, B, C	Data Select Inputs
15 - 9, 7	Y1-Y8	Data Outputs
8	GND	Ground (0V)
4, 5, 6	$\overline{G2A}$ , $\overline{G2B}$ , G1	Enable Inputs
16	VDD	Positive power supply

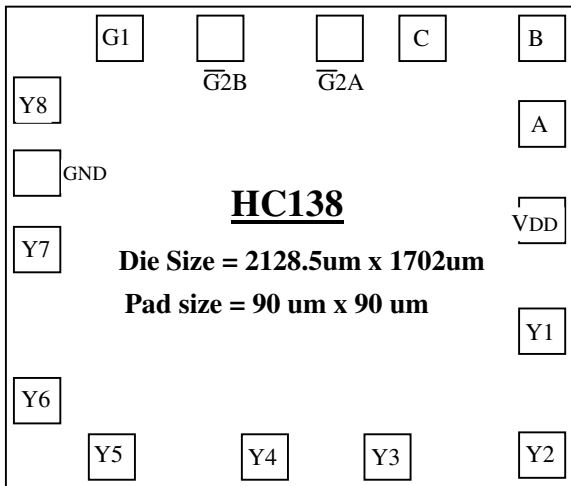


Pin Configuration



Logic Symbol

**PAD DIAGRAM**



The Coordinate of Each Pad

A	(429.4, 178.2)	Y7	(-519.3, -57.4)
B	(429.4, 337.7)	Y6	(-519.3, -342.8)
C	(206.4, 337.7)	Y5	(-381.2, -446.8)
G2A	(48.2, 337.7)	Y4	(-92.1, -446.8)
G2B	(-174.8, 337.7)	Y3	(139.9, -446.8)
G1	(-365.3, 337.7)	Y2	(428.7, -446.8)
Y8	(-519.3, 222.8)	Y1	(429.4, -210.4)
GND	(-519.3, 82.7)	VDD	(429.4, -3.3)

**Note:** Substrate should be connected to VDD or left it open.

**PAD IDENTIFICATION**

